

General Description

SXG60N10D use advanced SGT MOSFET technology to provide low RDS(ON), low gate charge, fast switching and excellent avalanche characteristics.

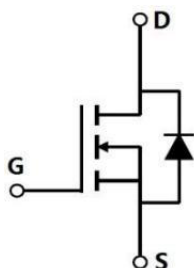
This device is specially designed to get better ruggedness and suitable to use in

Features

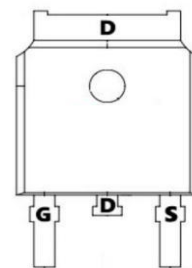
Low RDS(on) & FOM
Extremely low switching loss
Excellent stability and uniformity or Invertors

Applications

Consumer electronic power supply
Motor control
Synchronous-rectification
Isolated DC
Synchronous-rectification applications



TO-252-3L



Absolute Maximum Ratings at $T_J=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	V_{DS}	100	V
Gate source voltage	V_{GS}	± 20	V
Continuous drain current ¹⁾ , $T_C=25^\circ\text{C}$	I_D	60	A
Pulsed drain current ²⁾ , $T_C=25^\circ\text{C}$	$I_{D, \text{ pulse}}$	180	A
Power dissipation ³⁾ , $T_C=25^\circ\text{C}$	P_D	125	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	100	mJ
Operation and storage temperature	T_{stg}, T_J	-55 to 150	$^\circ\text{C}$
Thermal resistance, junction-case	$R_{\theta JC}$	1	$^\circ\text{C/W}$
Thermal resistance, junction-ambient ⁴⁾	$R_{\theta JA}$	62	$^\circ\text{C/W}$

Electrical Characteristics at $T_J=25\text{ }^{\circ}\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BVDSS	100			V	$V_{GS}=0\text{ V}$, $I_D=250\text{ }\mu\text{A}$
Gate threshold voltage	$V_{GS(th)}$	1.0		2.5	V	$V_{DS}=V_{GS}$, $I_D=250\text{ }\mu\text{A}$
Drain-source on-state resistance	$R_{DS(ON)}$		8	10	$\text{m}\Omega$	$V_{GS}=10\text{ V}$, $I_D=10\text{ A}$
Drain-source on-state resistance	$R_{DS(ON)}$		10	12	$\text{m}\Omega$	$V_{GS}=4.5\text{ V}$, $I_D=10\text{ A}$
Gate-source leakage current	IGSS			100	nA	$V_{GS}=20\text{ V}$
				-100		$V_{GS}=-20\text{ V}$
Drain-source leakage current	IDSS			1	μA	$V_{DS}=100\text{ V}$, $V_{GS}=0\text{ V}$
Input capacitance	Ciss		2604		pF	$V_{GS}=0\text{ V}$, $V_{DS}=50\text{ V}$, $f=1\text{ MHz}$
Output capacitance	Coss		361.2		pF	
Reverse transfer capacitance	Crss		6.5		pF	
Turn-on delay time	$t_{d(on)}$		20.6		ns	$V_{GS}=10\text{ V}$, $V_{DS}=50\text{ V}$, $R_G=2.2\text{ }\Omega$, $I_D=25\text{ A}$
Rise time	t_r		5		ns	
Turn-off delay time	$t_{d(off)}$		51.8		ns	
Fall time	t_f		9		ns	
Total gate charge	Q_g		49.9		nC	$I_D=25\text{ A}$, $V_{DS}=50\text{ V}$, $V_{GS}=10\text{ V}$
Gate-source charge	Q_{gs}		6.5		nC	
Gate-drain charge	Q_{gd}		12.4		nC	
Gate plateau voltage	$V_{plateau}$		3.4		V	
Diode forward current	I_S			60		$V_{GS}<V_{th}$
Pulsed source current	ISP			180	A	
Diode forward voltage	VSD			1.3	V	$I_S=12\text{ A}$, $V_{GS}=0\text{ V}$
Reverse recovery time	t_{rr}		60.4		ns	$I_S=12\text{ A}$, $di/dt=100\text{ A}/\mu\text{s}$
Reverse recovery charge	Q_{rr}		106.1		nC	
Peak reverse recovery current	I_{rrm}		3		A	

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25\text{ }^{\circ}\text{C}$.
- 5) $V_{DD}=50\text{ V}$, $R_G=25\text{ }\Omega$, $L=0.3\text{ mH}$, starting $T_J=25\text{ }^{\circ}\text{C}$.

Typical Characteristics

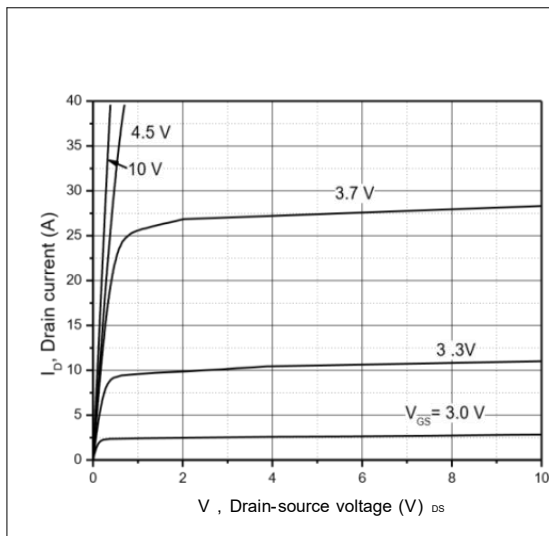


Figure 1, Typ. output characteristics

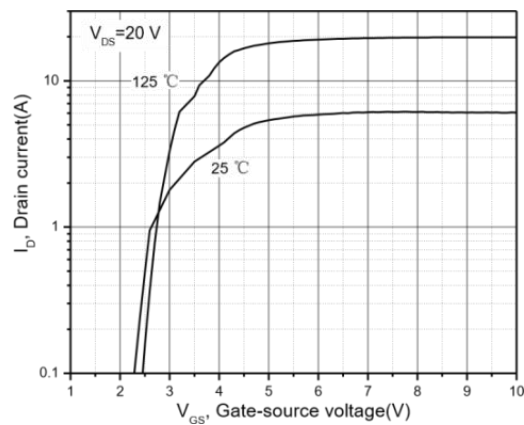


Figure 2, Typ. transfer characteristics

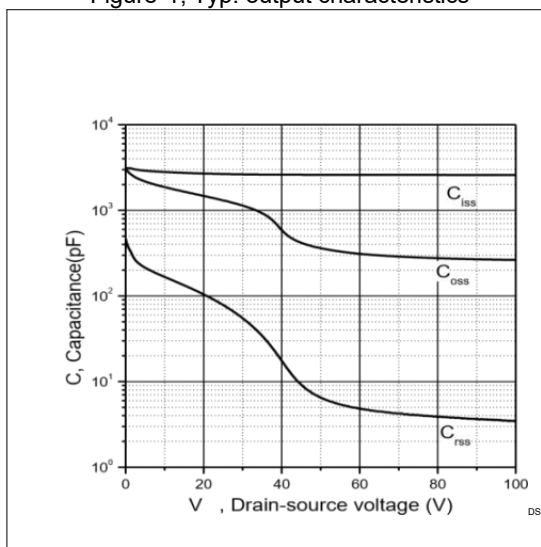


Figure 3, Typ. capacitances

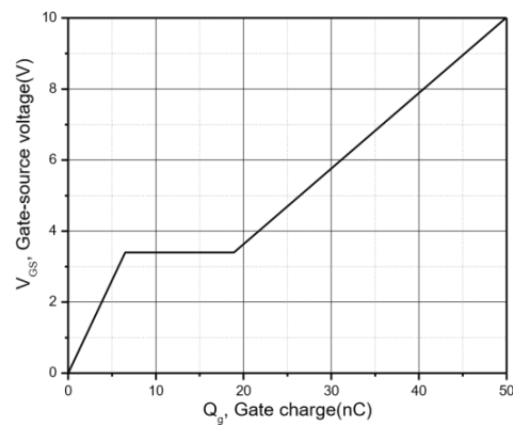


Figure 4, Typ. gate charge

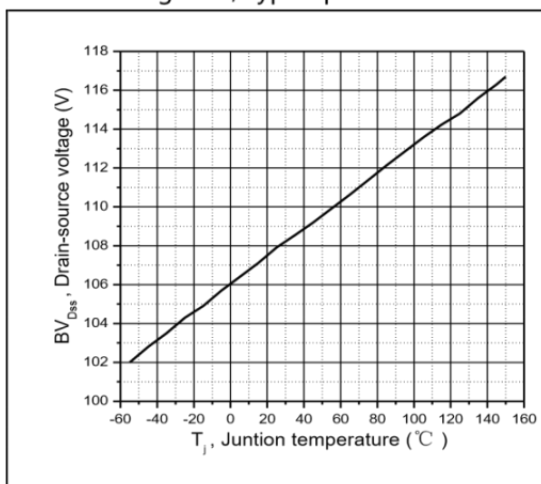


Figure 5, Drain-source breakdown voltage

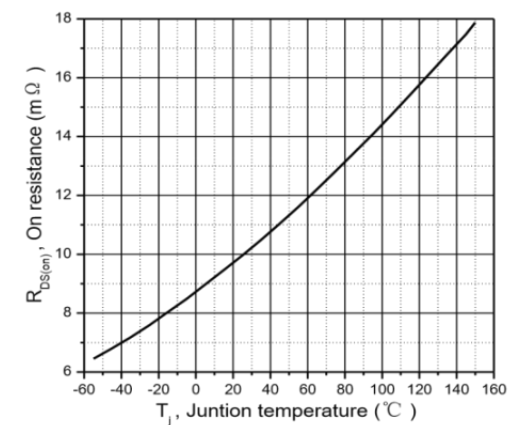


Figure 6, Drain-source on-state resistance

Typical Characteristics

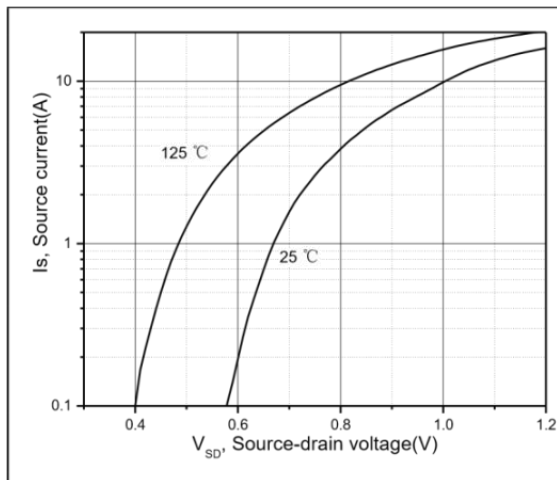


Figure 7, Forward characteristic of body diode

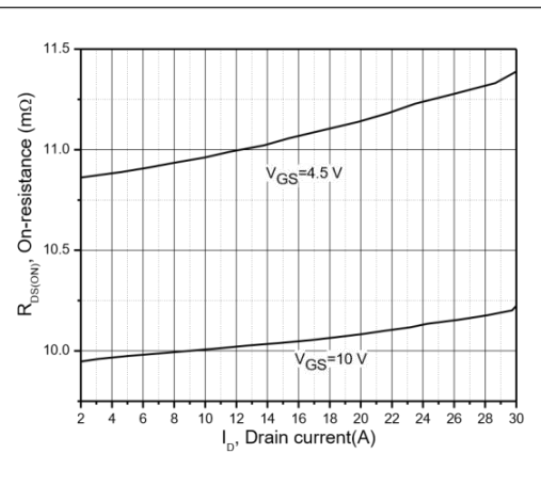


Figure 8, Drain-source on-state resistance

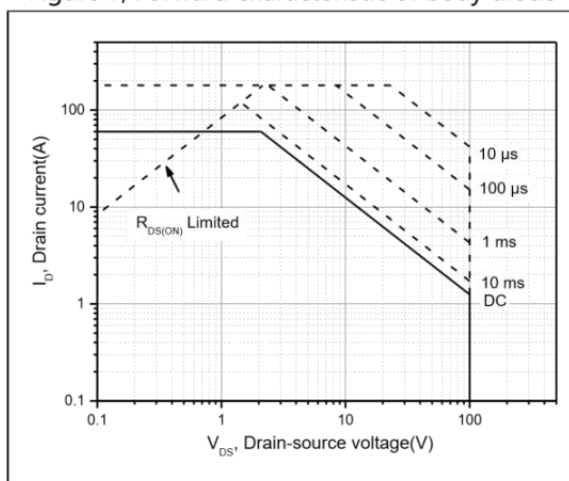


Figure 9, Safe operation area $T_C = 25\text{ }^{\circ}C$

Test circuits and waveforms

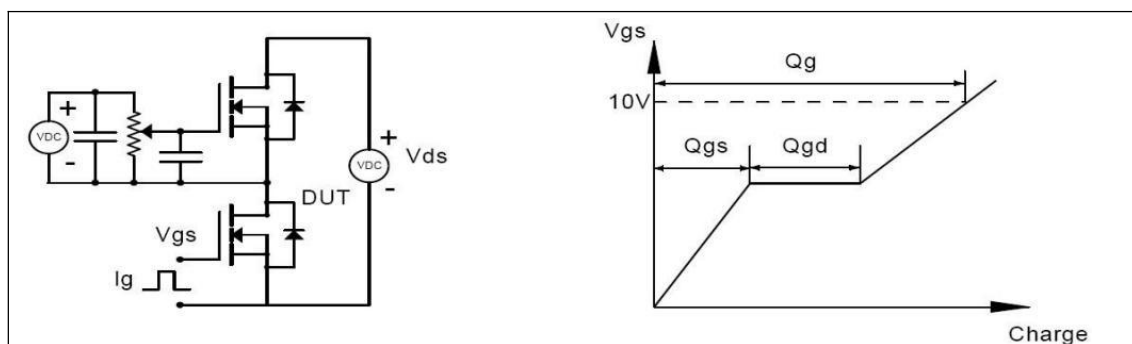


Figure 1, Gate charge test circuit & waveform

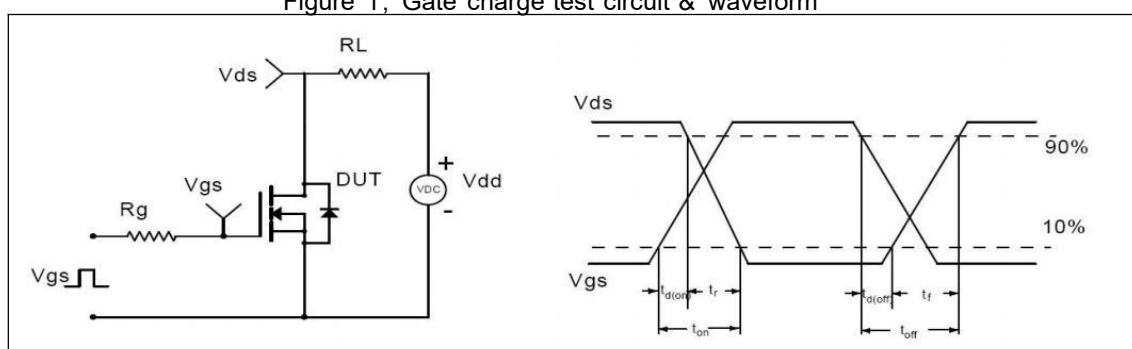


Figure 2, Switching time test circuit & waveforms

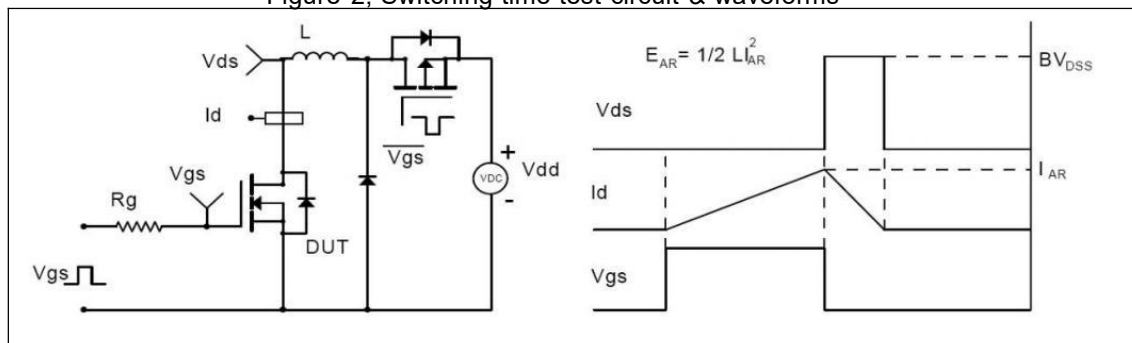


Figure 3, Unclamped inductive switching (UIS) test circuit & waveforms

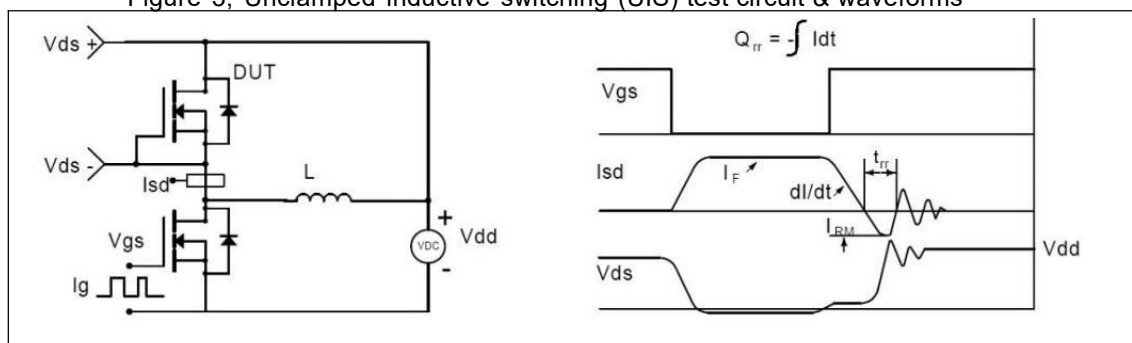
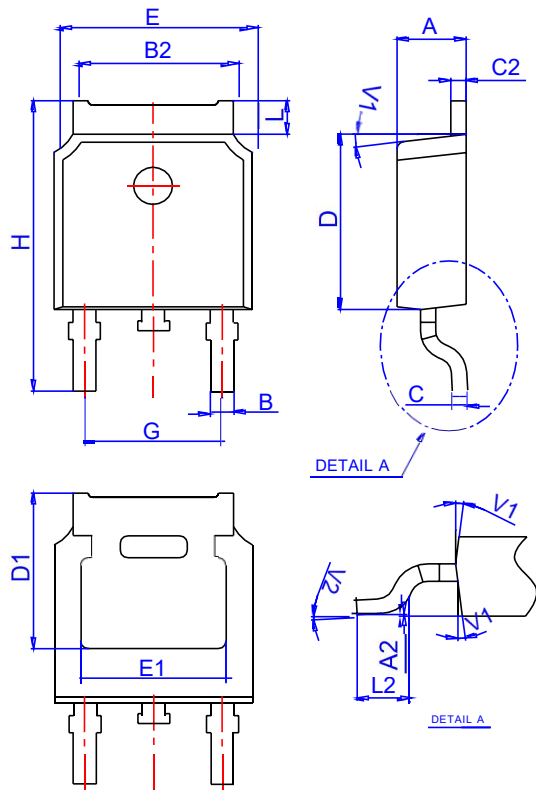


Figure 4, Diode reverse recovery test circuit & waveforms

Package Mechanical Data: TO-252-3L



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	TO-252-3L		2500